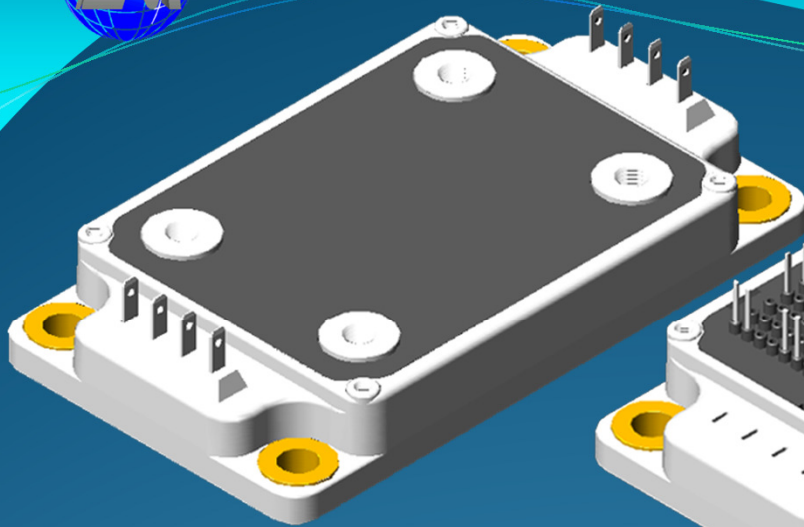
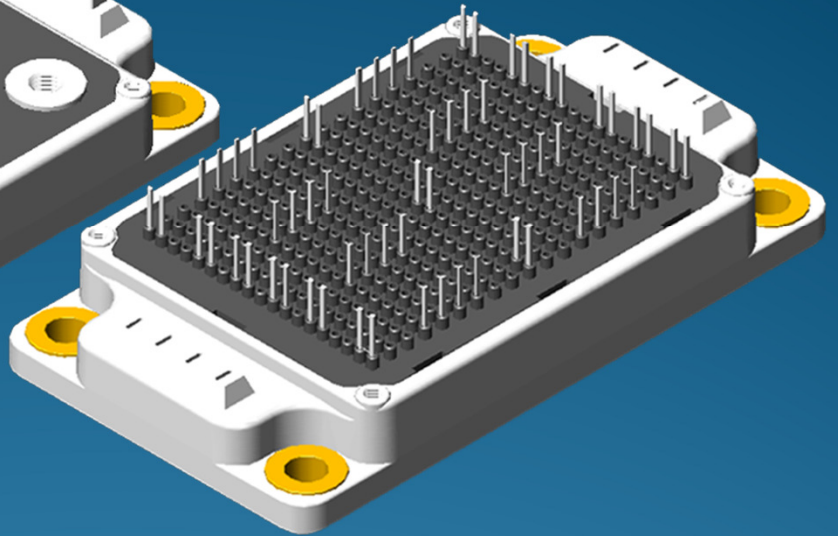




Team Pacific Corporation



High Power Module



Intelligent Power Module

## Versatile Power Module Package

This Versatile power module package features a robust and flexible design and easy integration with other components using solderless connections. The package is also ideal for high power application and perfectly fits a variety of circuit configurations.

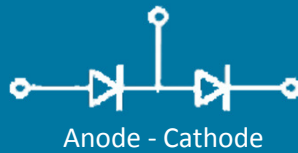
### Main features:

- Compact module design.
- PressFit technology signal terminal and screw type power terminals for completely solderless connections.
- High power density; can handle up to 300 Amperes and 1700 Volts.
- Corner mounting holes for better heatsinking.
- Elevated signal terminals for better creepage distance.
- Configuration flexibility; Diode, Thyristor, IGBT, Mosfet and Intelligent circuit configuration.



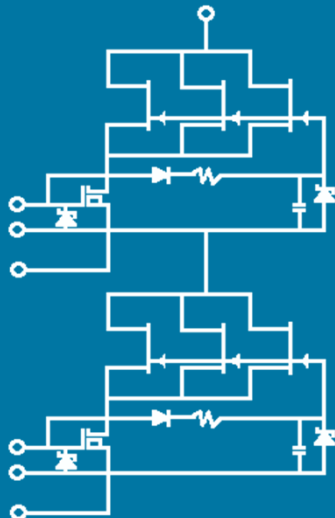
## Sample Module Circuit Configurations:

### Diode and Thyristor Configurations

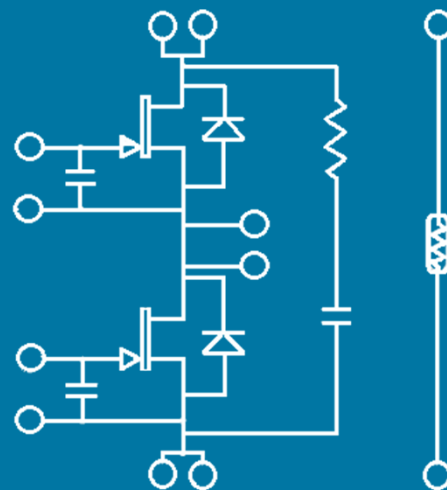


### Inverter Configurations

Half Bridge Cascade Inverter

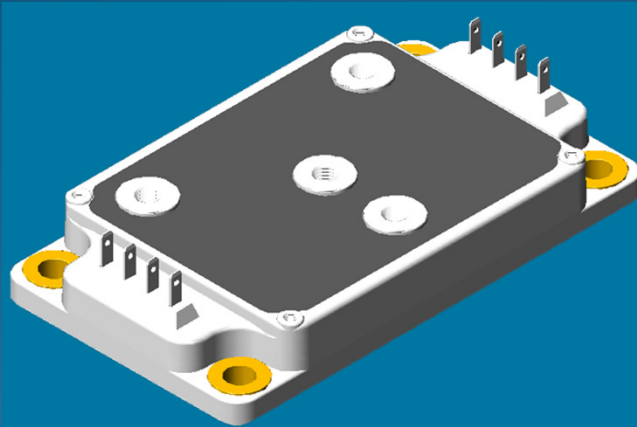


Half Bridge / Single Phase Inverter





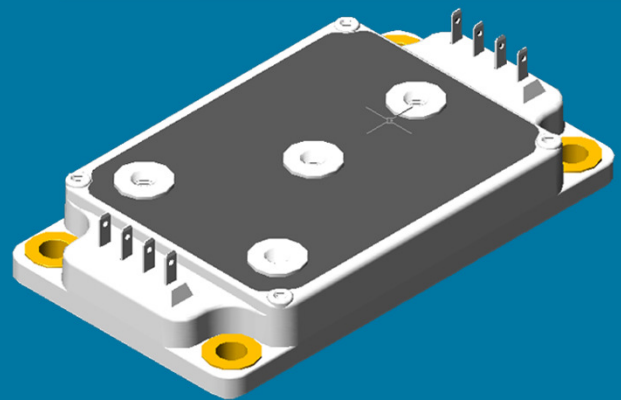
## Power Module Variants



### 4 Power Terminals

Applicable configurations:

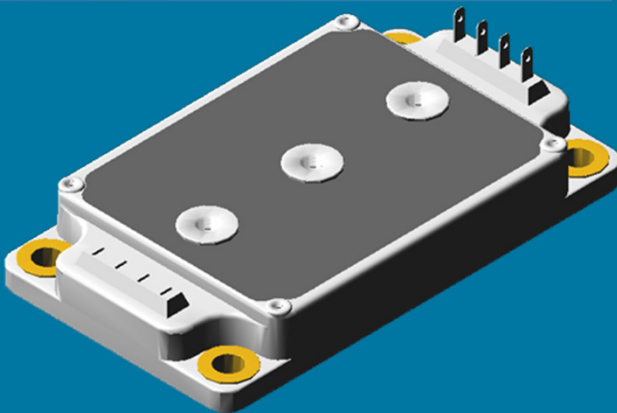
- Diode-Diode
- Diode- Thyristor
- Thyristor-Thyristor
- Half Bridge Cascade Inverter
- Single / Multi Phase Inverter



### 3 Power Terminals

Applicable configurations:

- Diode-Diode
- Diode- Thyristor
- Thyristor-Thyristor

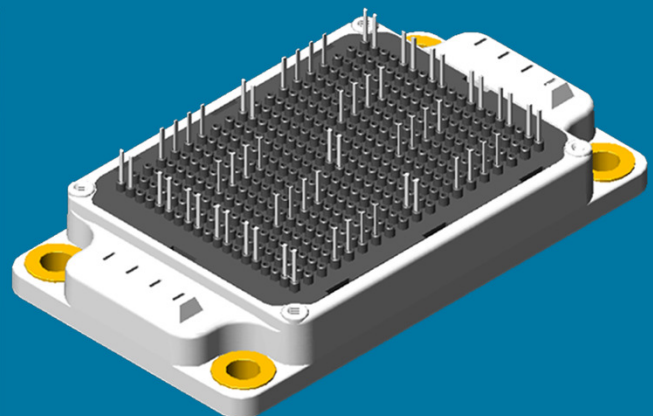


### Intelligent Power Module

Applicable configurations:

- Single / Multi Phase Power Inverter
- Cascade Inverter
- Multi-Controller Inverter

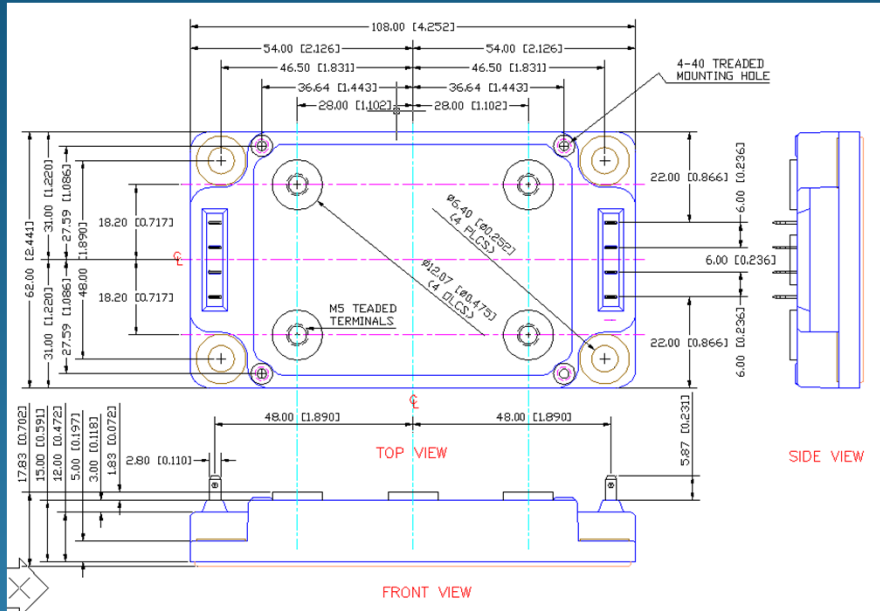
Note: An option is available for a low profile package for low inductance requirement.





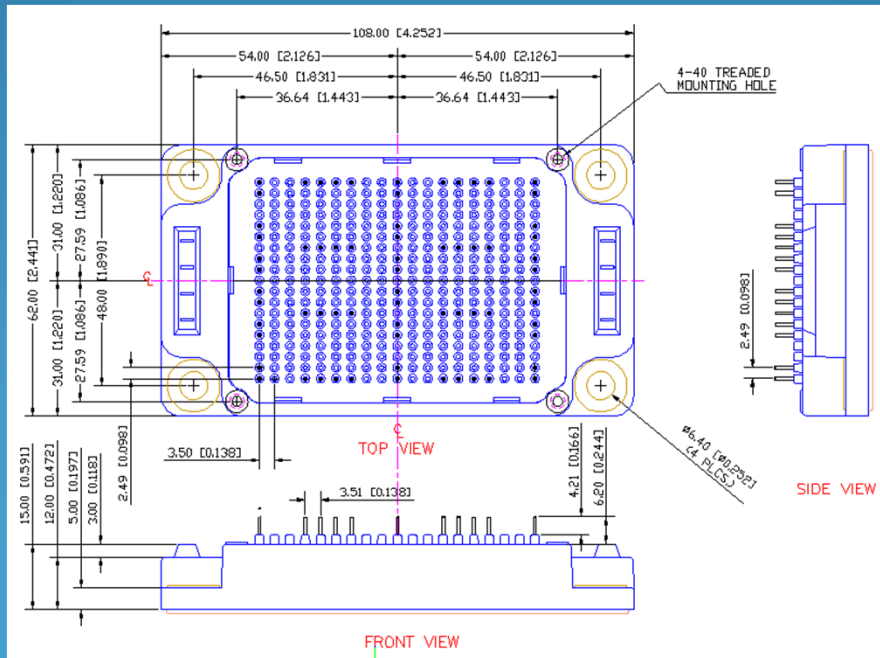
# Package Outline Design

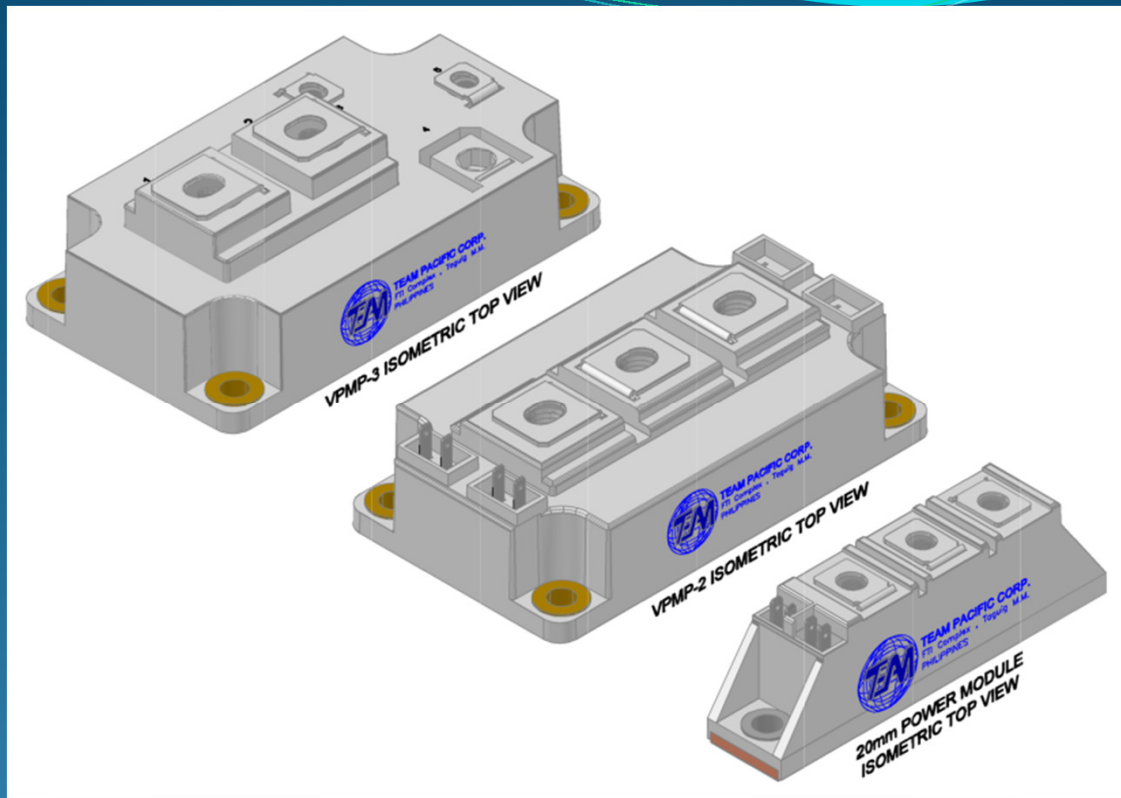
## High Power Module



Note: An option is available for M5 Power Screw Terminal

## Intelligent Power Module





## Versatile Power Module Package

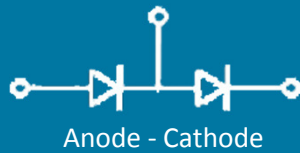
The TPC power module package features a robust and flexible design and easy integration with other components using solderless connections. The package is also ideal for high power application and perfectly fits a variety of circuit configurations.

### Main features:

- Compact module design.
- PressFit technology signal terminal and screw type power terminals for completely solderless connections.
- High power density;
  - VPMP2 can handle 300-400 Amperes and 1700 Volts.
  - VPMP3 can handle up to 600 Amperes and 1700 Volts.
  - 20mm can handle 100 to 200 Amperes and 1700 Volts.
- Corner mounting holes for VPMP2 and VPMP3, and 2 holes for 20mm for better heatsinking.
- Configuration flexibility; Diode, Thyristor, IGBT, Mosfet and Intelligent circuit configuration.



Sample Circuit Configuration for 20mm



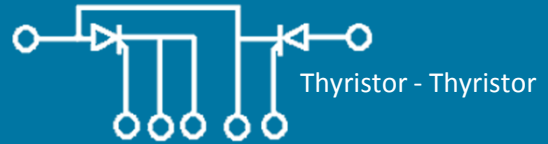
Anode - Cathode



Common Cathode



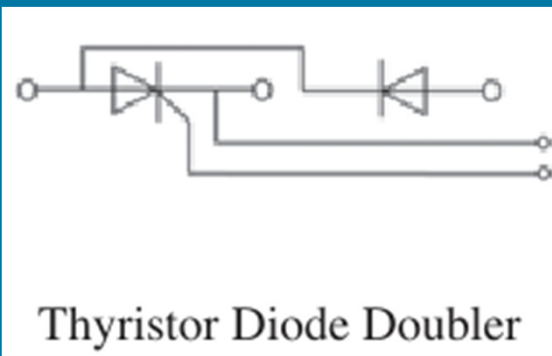
Common Anode



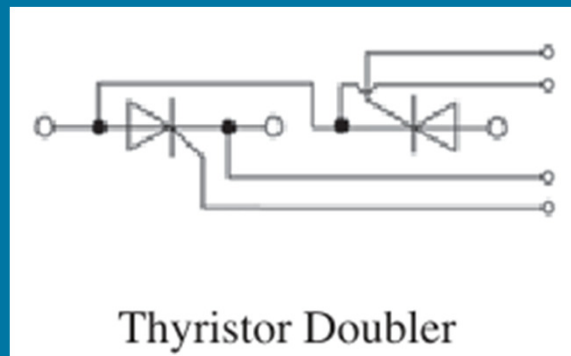
Thyristor - Thyristor



Thyristor - Diode



Thyristor Diode Doubler

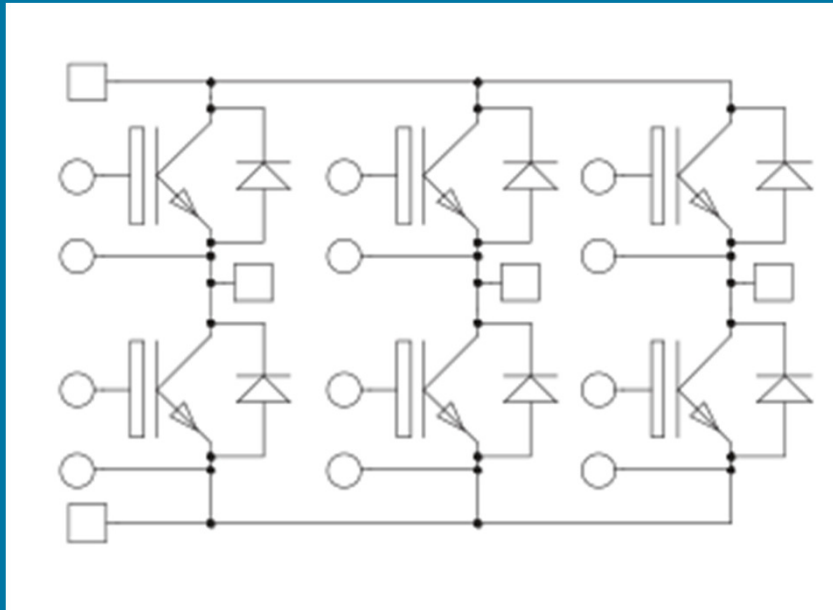


Thyristor Doubler



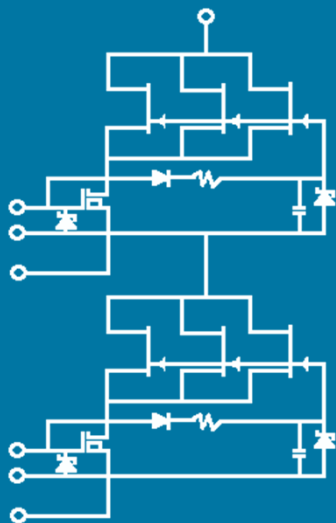
Sample Circuit Configuration for VPMP2

3 PHASE BRIDGE

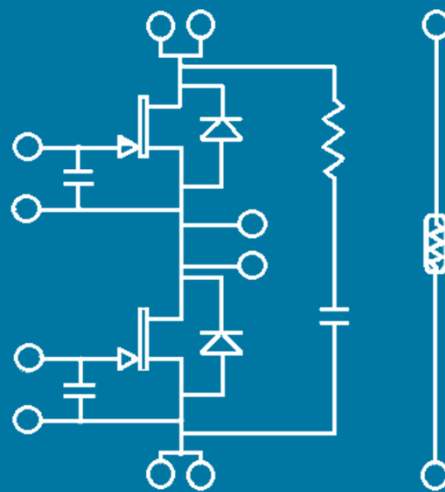


Inverter Configurations

Half Bridge Cascade Inverter



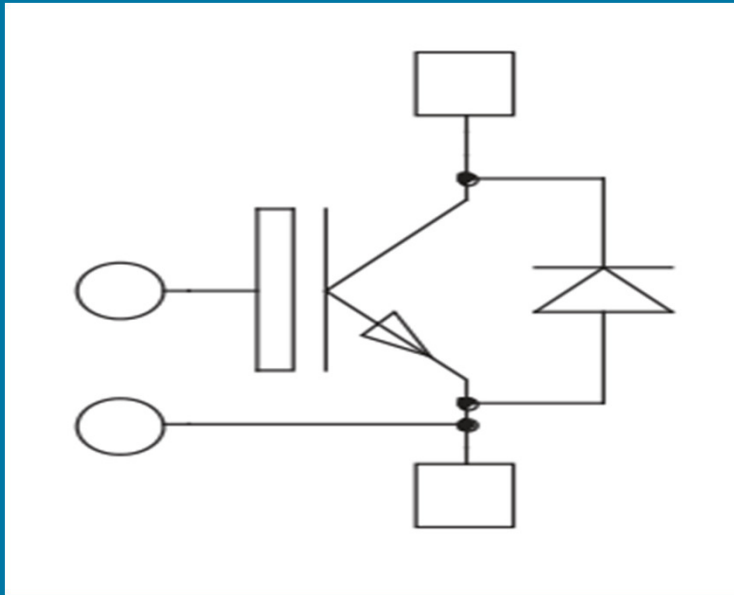
Half Bridge / Single Phase Inverter





Sample Circuit Configuration for VPMP3

SINGLE SWITCH



SINGLE SWITCH + SERIES DIODE

